Foil-Format Grease Replacement for Maximum Heat Transfer

Features and Benefits

- Thermal impedance: 0.22°C-in²/W (@50 psi)
- · Maximum heat transfer
- · Aluminum foil coated both sides
- Designed to replace thermal grease



Q-Pad II is a composite of aluminum foil coated on both sides with thermally / electrically conductive Sil-Pad rubber. The material is designed for those applications in which maximum heat transfer is needed and electrical isolation is not required. Q-Pad II is the ideal thermal interface material to replace messy thermal grease compounds.

Q-Pad II eliminates problems associated with grease such as contamination of reflow solder or cleaning operations. Unlike grease, Q-Pad II can be used prior to these operations. Q-Pad II also eliminates dust collection which can cause possible surface shorting or heat buildup.

TYPICAL PROPERTIES OF Q-PAD II						
PROPERTY	IMPERIAL VALUE		METRIC VALUE		TEST METHOD	
Color	Black		Black		Visual	
Reinforcement Carrier	Aluminum		Aluminum		_	
Thickness (inch) / (mm)	0.006		0.152		ASTM D374	
Hardness (Shore A)	93		93		ASTM D2240	
Continuous Use Temp (°F) / (°C)	-76 to 356		-60 to 180		_	
ELECTRICAL						
Dielectric Breakdown Voltage (Vac)	Non-Insulating		Non-Insulating		ASTM D149	
Dielectric Constant (1000 Hz)	NA		NA		ASTM D150	
Volume Resistivity (Ohm-meter)	10 ²		10 ²		ASTM D257	
Flame Rating	V-O		V-O		U.L.94	
THERMAL						
Thermal Conductivity (W/m-K)	2.5		2.5		ASTM D5470	
THERMAL PERFORMANCE vs PRESSURE						
Press	sure (psi)	10	25	50	100	200
TO-220 Thermal Performance (°C/W)		2.44	1.73	1.23	1.05	0.92
Thermal Impedance (°C-in²/W) (1)		0.52	0.30	0.22	0.15	0.12
1) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for						

1) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

Typical Applications Include:

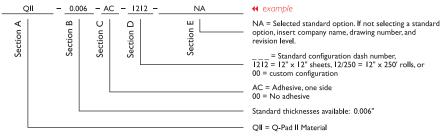
- Between a transistor and a heat sink
- Between two large surfaces such as an L-bracket and the chassis of an assembly
- Between a heat sink and a chassis
- Under electrically isolated power modules or devices such as resistors, transformers and solid state relays

Configurations Available:

- Sheet form, die-cut parts and roll form
- With or without pressure sensitive adhesive

Building a Part Number

Standard Options



Note: To build a part number, visit our website at www.bergquistcompany.com.

Sil-Pad*: U.S. Patents 4,574,879; 4,602,125; 4,602,678; 4,685,987; 4,842,911 and others

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Bergquist Company:

QII-0.006-AC-1212-NA QII-0.006-00-1212-NA QII-0.006-AC-1212 QII-0.006-00-101 QII-0.006-00-1212